BENEQ TFS 500

VERSATILE PLATFORM
FOR ALD R&D AND PRODUCTION

PROCESS TYPE	• thermal ALD • plasma enhanced ALD
USAGE	• production • R&D
SUBSTRATE TYPE	• up to 300mm wafer • 370x470mm glass • 300x420mm batch • 3D-parts • powder
SUBSTRATE LOADING	• automatic • manual
MAIN DIMENSIONS	• 1600×900×1930 mm
INTEGRATION	• glove box • load-lock • cluster

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Process temperature range	25 - 500 °C
Reaction chamber types and dimensions	- Single wafer: ø200 × 18 (mm), ø300 × 18 (mm) - Single wafer plasma: ø200 × 18 (mm), ø300 × 18 (mm) - 3D/batch of wafers: ø200 × 170 (mm) - 3D/batch: 450 × 300 × 250 (mm) - Powder: ø80 × 50 (mm) - Solar cell batch: 156 × 156 (mm), 100 pcs
Gas lines	Up to 5
Liquid sources (+5 °C to ambient)	Up to 4
Hot source HS 300 (ambient to 300 °C)	Up to 4
Hot source HS 500 (ambient to 500 °C)	Up to 2
Optional	CCP plasma source (capacitively coupled)
Control system	PLC control with PC user interface
Main dimensions	1600 × 900 × 1930 (mm)